



# PMEG060T080CLPE

60 V, 2 x 4 A dual common cathode low leakage current  
Trench MEGA Schottky barrier rectifier

27 April 2020

Product data sheet

## 1. General description

Trench Maximum Efficiency General Application (MEGA) dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Reverse voltage:  $V_R \leq 60$  V
- Forward current:  $I_F \leq 4$  A (per diode)
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- High power capability due to clip-bond technology
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Freewheeling applications

## 4. Quick reference data

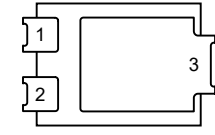
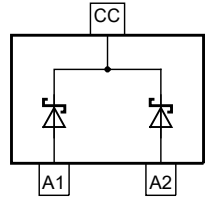
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode (unless otherwise specified)</b>						
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square wave; $f = 20$ kHz; $T_{sp} \leq 160$ °C	-	-	4	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	60	V
$V_F$	forward voltage	$I_F = 4$ A; $T_j = 25$ °C	[1]	580	660	mV
$I_R$	reverse current	$V_R = 10$ V; $T_j = 25$ °C	[1]	0.14	0.9	$\mu$ A
		$V_R = 60$ V; $T_j = 25$ °C	[1]	0.3	1.8	$\mu$ A

[1] Very short pulse, in order to maintain a stable junction temperature.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)	 <p>CFP15B (SOT1289B)</p>	 <p>006aab034</p>
2	A2	anode (diode 2)		
3	CC	common cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
PMEG060T080CLPE	CFP15B	plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG060T080CLPE	060T L08C

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
<b>Per diode (unless otherwise specified)</b>						
$V_R$	reverse voltage	$T_j = 25\text{ °C}$	-	60	V	
$I_F$	forward current	$\delta = 1; T_{sp} \leq 156\text{ °C}$	-	5.7	A	
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square wave; $f = 20\text{ kHz}$ ; $T_{sp} \leq 160\text{ °C}$	-	4	A	
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8.3\text{ ms}$ ; half sine wave; $T_{j(init)} = 25\text{ °C}$	-	80	A	
		$t_p = 8.3\text{ ms}$ ; half sine wave; per device; $T_{j(init)} = 25\text{ °C}$	-	150	A	
<b>Per device, one diode loaded</b>						
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	-	1.66	W
			[2]	-	2.15	W
$T_j$	junction temperature		-	175	°C	
$T_{amb}$	ambient temperature		-55	175	°C	
$T_{stg}$	storage temperature		-65	175	°C	

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Per device, one diode loaded</b>							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

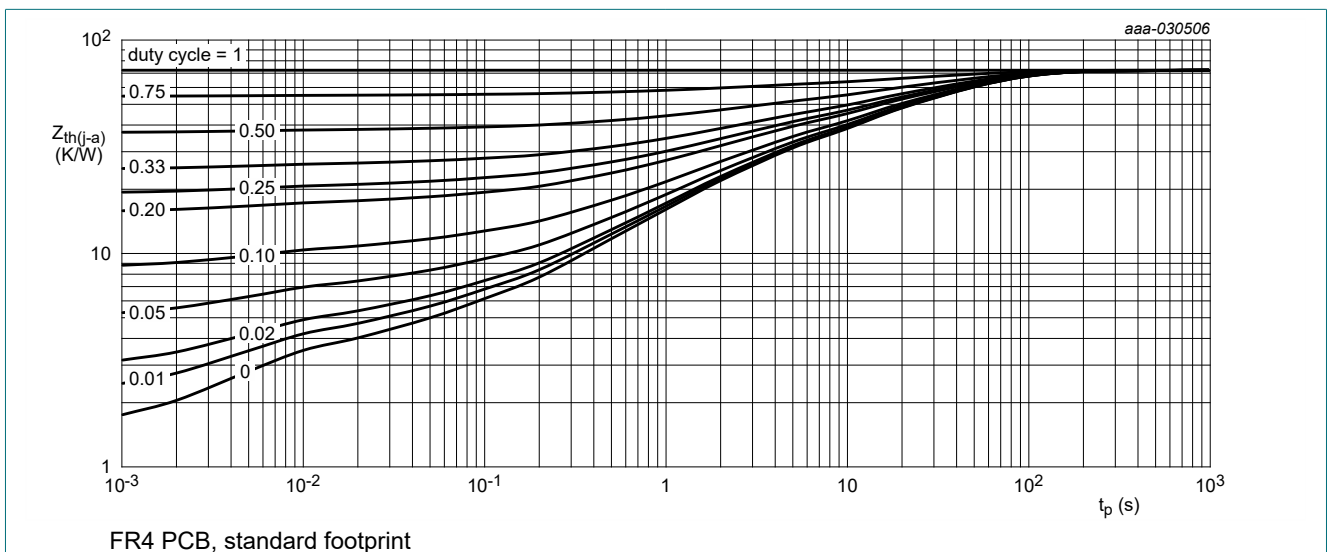


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

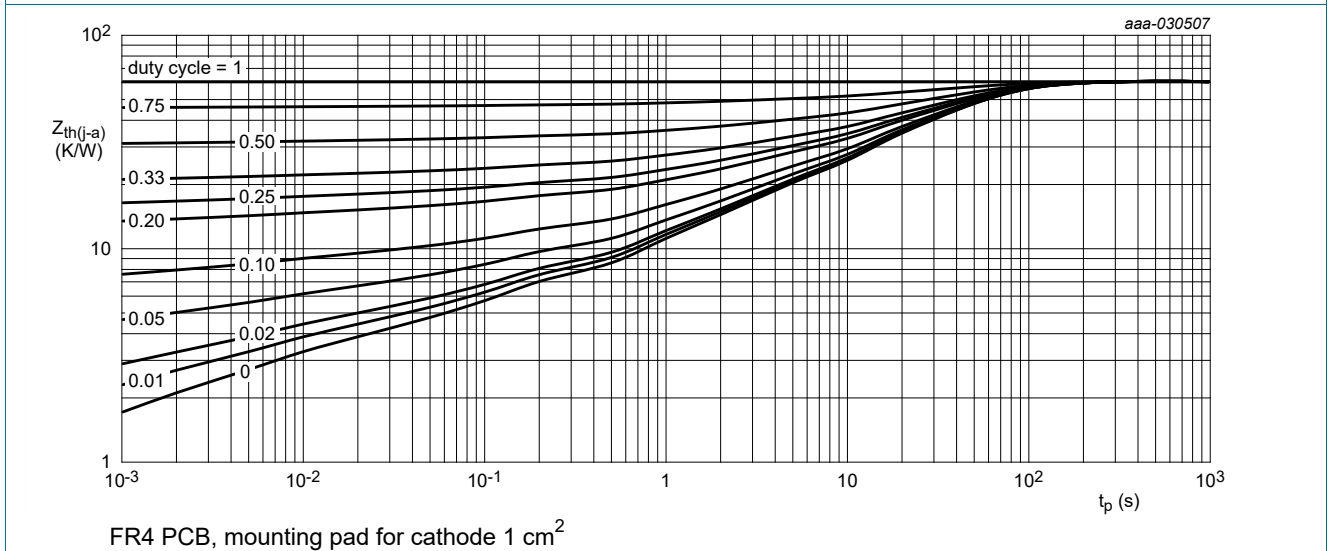


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

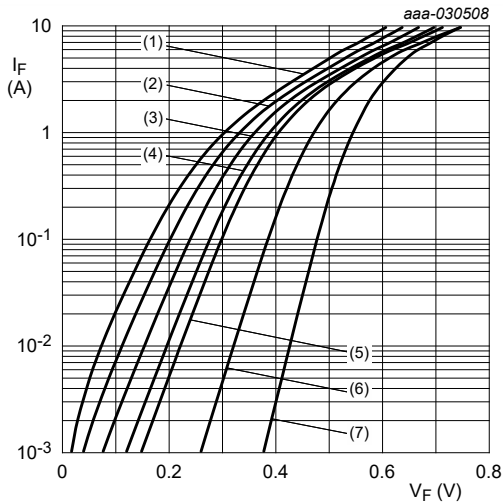
## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Per diode (unless otherwise specified)</b>							
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	[1]	60	-	-	V
$V_F$	forward voltage	$I_F = 0.5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	440	510	mV
		$I_F = 1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	470	540	mV
		$I_F = 4 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	580	660	mV
		$I_F = 4 \text{ A}; T_j = -40 \text{ }^\circ\text{C}$	[1]	-	630	720	mV
		$I_F = 4 \text{ A}; T_j = 125 \text{ }^\circ\text{C}$	[1]	-	520	610	mV
$I_R$	reverse current	$V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	0.14	0.9	$\mu\text{A}$
		$V_R = 40 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	0.18	1.2	$\mu\text{A}$
		$V_R = 60 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	[1]	-	0.3	1.8	$\mu\text{A}$
		$V_R = 60 \text{ V}; T_j = 125 \text{ }^\circ\text{C}$	[1]	-	0.5	3	mA
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$		-	560	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$		-	180	-	pF
$t_{rr}$	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(\text{meas})} = 0.1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A}/\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	11	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}$		-	460	-	mV

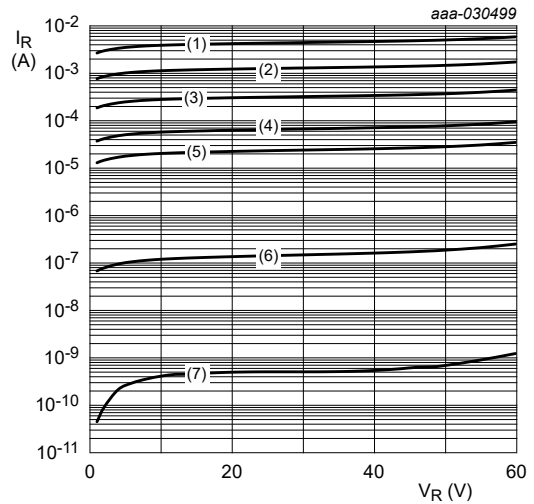
[1] Very short pulse, in order to maintain a stable junction temperature.

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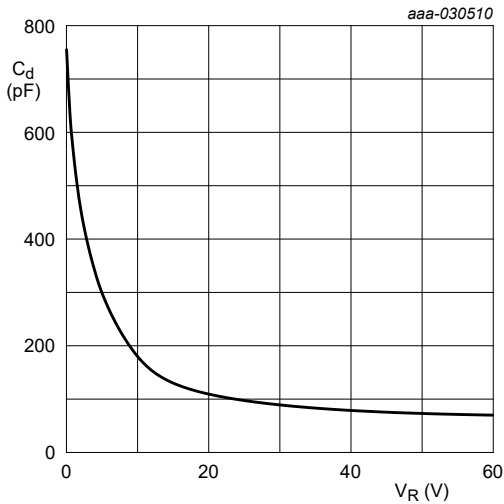
pulsed condition  
 (1)  $T_j = 175\text{ }^\circ\text{C}$   
 (2)  $T_j = 150\text{ }^\circ\text{C}$   
 (3)  $T_j = 125\text{ }^\circ\text{C}$   
 (4)  $T_j = 100\text{ }^\circ\text{C}$   
 (5)  $T_j = 85\text{ }^\circ\text{C}$   
 (6)  $T_j = 25\text{ }^\circ\text{C}$   
 (7)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 3. Forward current as a function of forward voltage; typical values**



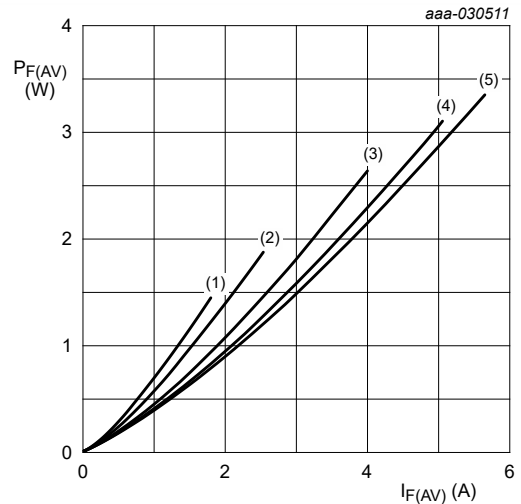
pulsed condition  
 (1)  $T_j = 175\text{ }^\circ\text{C}$   
 (2)  $T_j = 150\text{ }^\circ\text{C}$   
 (3)  $T_j = 125\text{ }^\circ\text{C}$   
 (4)  $T_j = 100\text{ }^\circ\text{C}$   
 (5)  $T_j = 85\text{ }^\circ\text{C}$   
 (6)  $T_j = 25\text{ }^\circ\text{C}$   
 (7)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 4. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

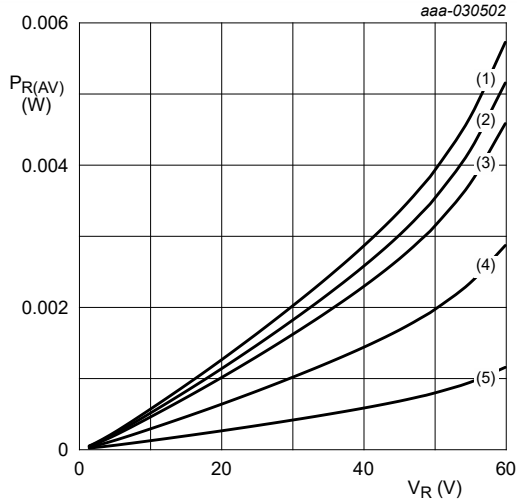
**Fig. 5. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 100\text{ }^\circ\text{C}$   
 (1)  $\delta = 0.1$   
 (2)  $\delta = 0.2$   
 (3)  $\delta = 0.5$   
 (4)  $\delta = 0.8$   
 (5)  $\delta = 1$ ; DC

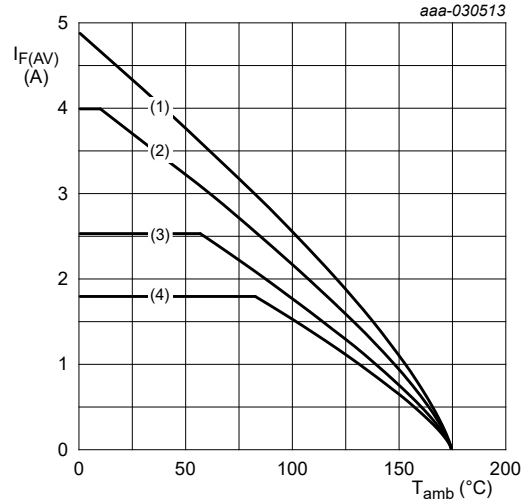
**Fig. 6. Average forward power dissipation as a function of average forward current; typical values**

60 V, 2 x 4 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier



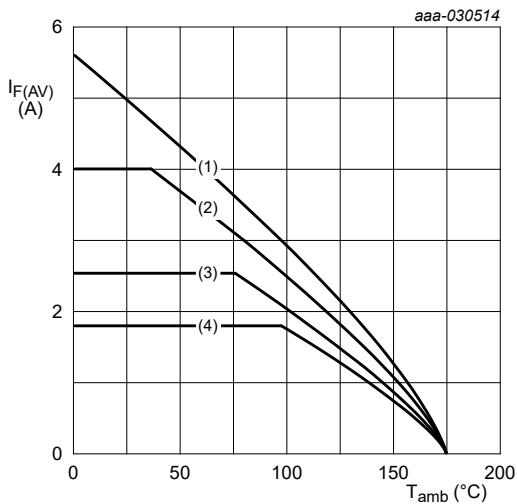
$T_j = 100\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.9$   
 (3)  $\delta = 0.8$   
 (4)  $\delta = 0.5$   
 (5)  $\delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



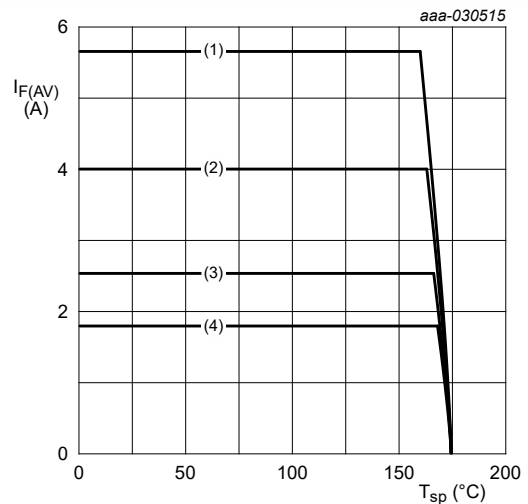
FR4 PCB, standard footprint  
 $T_j = 175\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 175\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

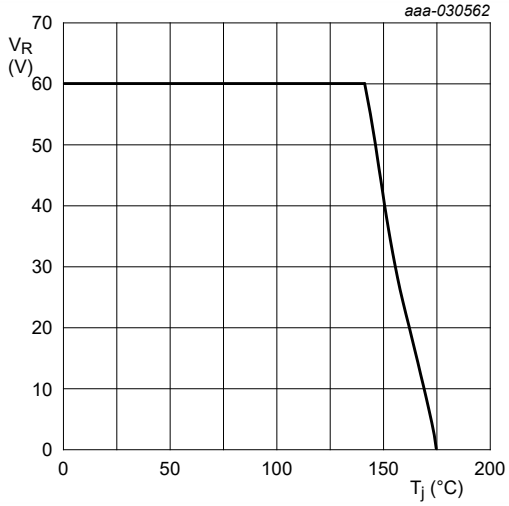
Fig. 9. Average forward current as a function of ambient temperature; typical values



$T_j = 175\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

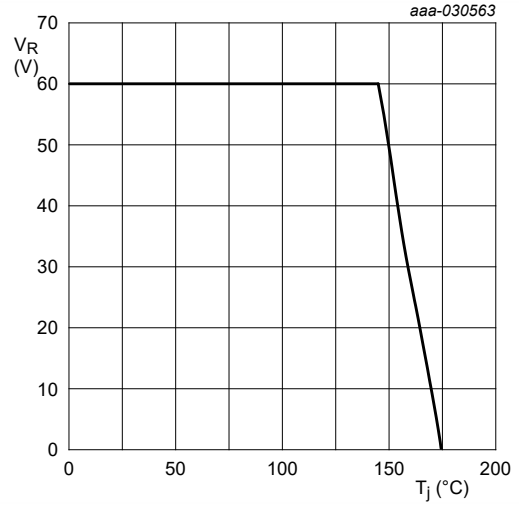
Fig. 10. Average forward current as a function of solder point temperature; typical values

60 V, 2 x 4 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier



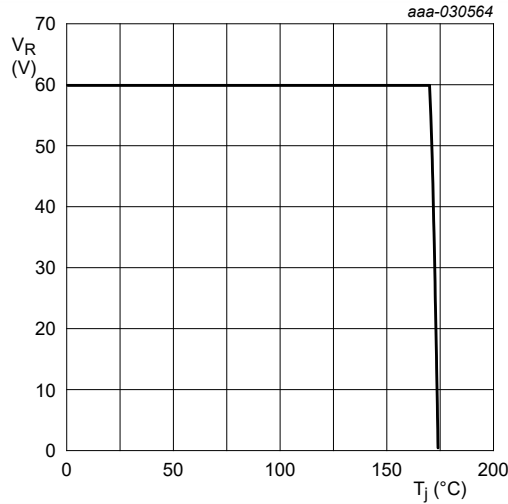
FR4 PCB, standard footprint  
R<sub>th</sub> = 90 K/W

Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
R<sub>th</sub> = 70 K/W

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab  
R<sub>th</sub> = 7 K/W

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

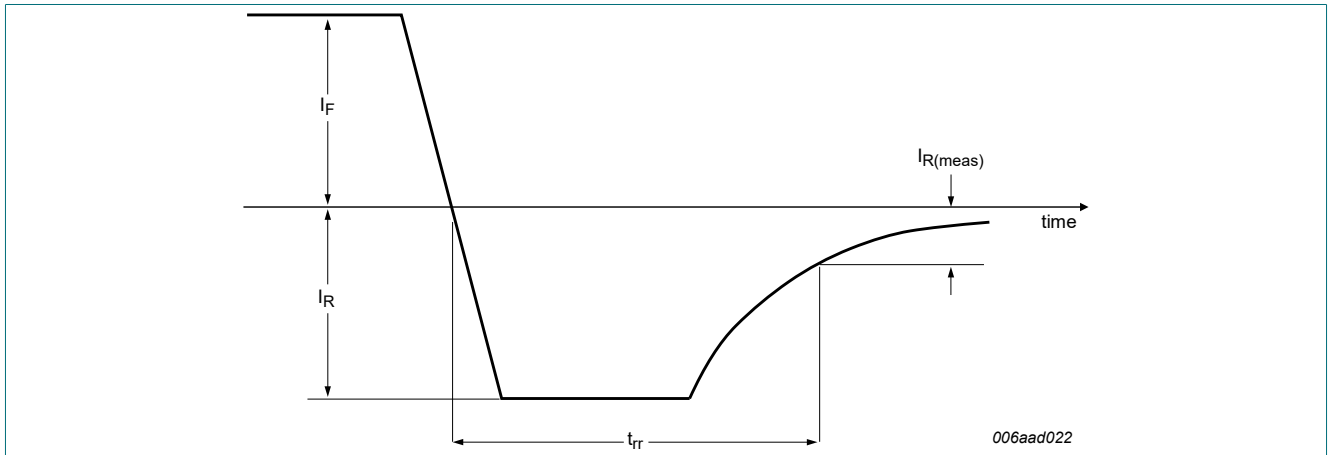


Fig. 14. Reverse recovery definition; step recovery

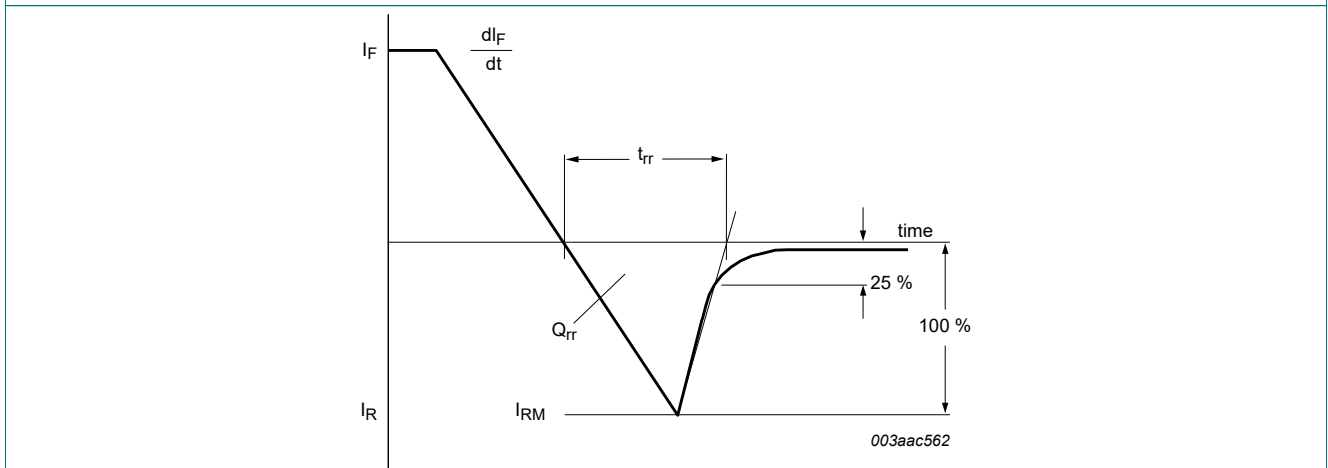


Fig. 15. Reverse recovery definition; ramp recovery

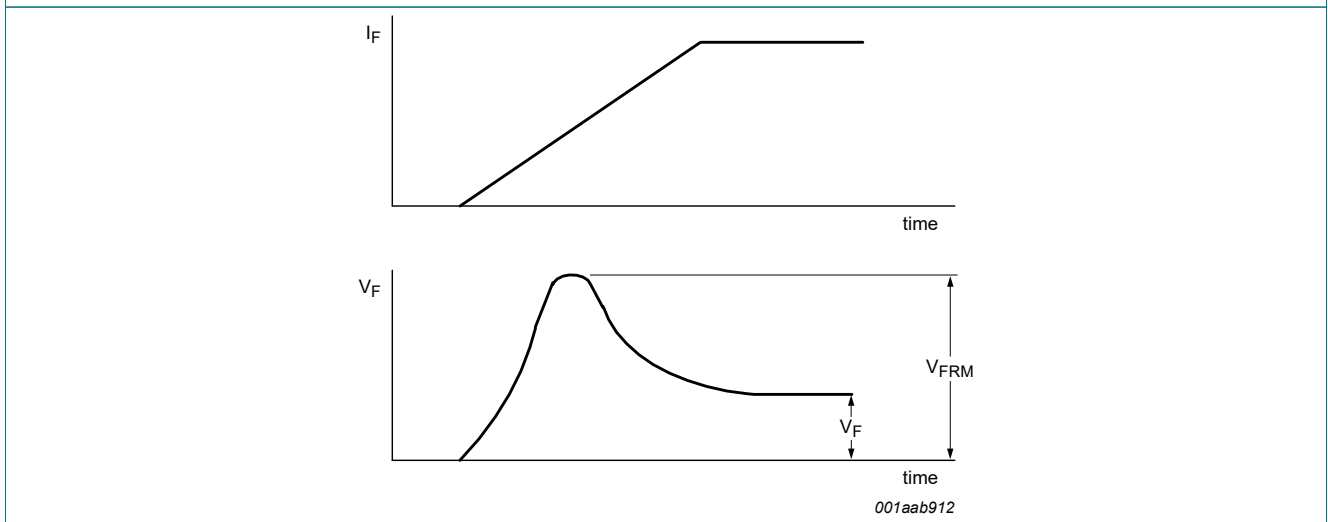


Fig. 16. Forward recovery definition



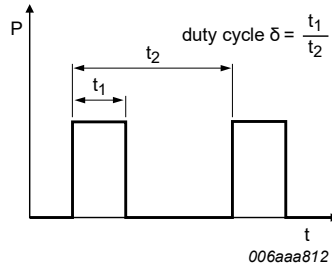


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta$$

with  $I_M$  defined as peak current

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with  $I_{RMS}$  defined as RMS current.

**Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

**12. Package outline**

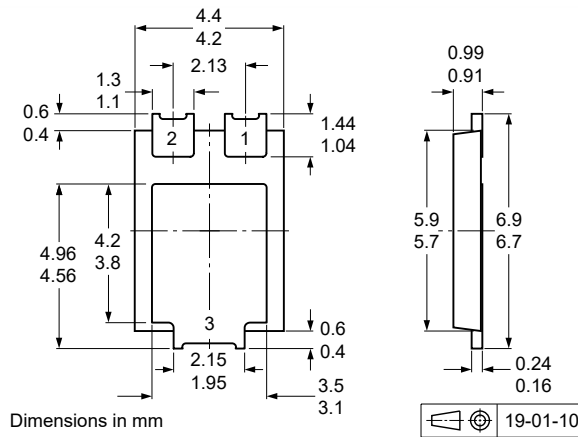
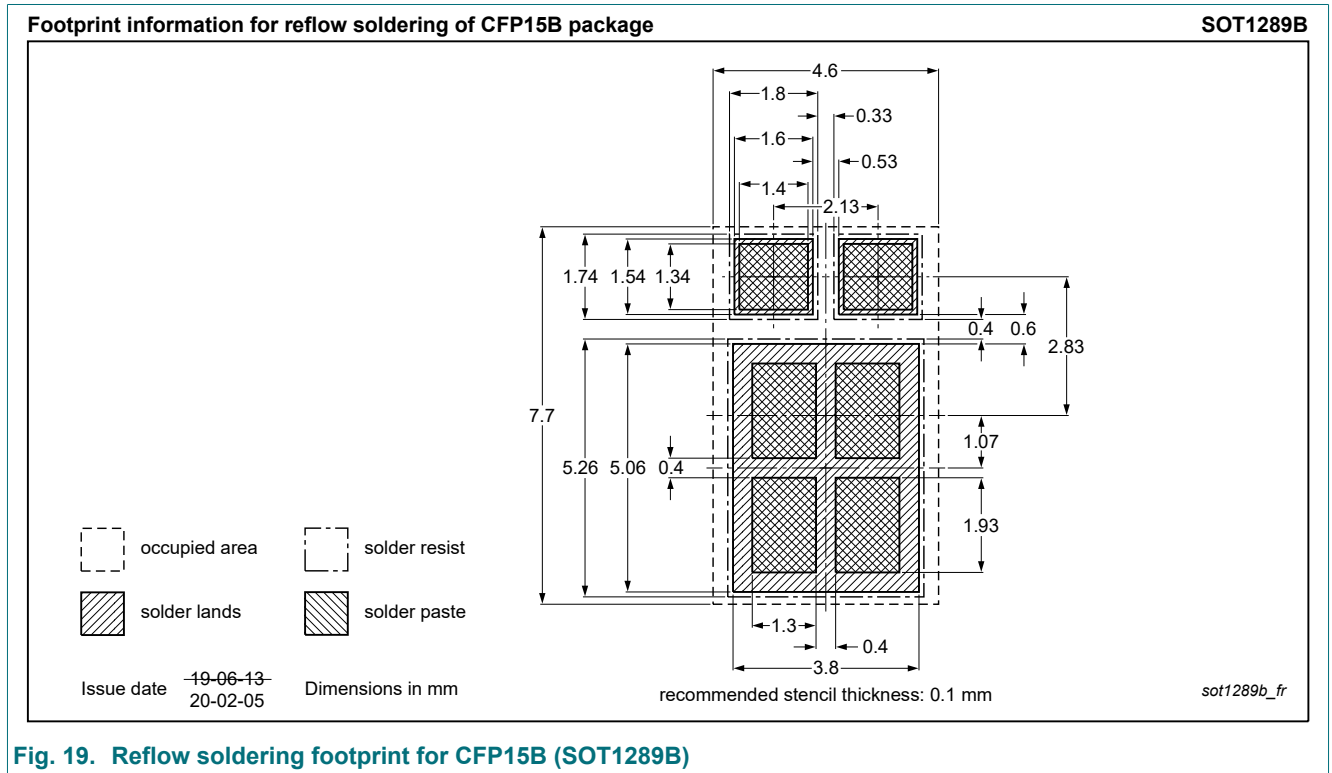


Fig. 18. Package outline CFP15B (SOT1289B)

### 13. Soldering



**Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG060T080CLPE v.2	20200427	Product data sheet	-	PMEG060T080CLPE v.1
Modifications:	• Product status changed			
PMEG060T080CLPE v.1	20200304	Objective data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 27 April 2020

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